



PATENT
Atty. Dkt. AMAT/6303/CPI/COPPER/PJS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:
Chung, Et Al.**

Serial No.: 09/965,370

Confirmation No.: 6507

Filed: September 26, 2001

For: Integration of Barrier Layer
and Seed Layer

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Group Art Unit: 1762

Examiner: Eric B. Fuller

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING 37 CFR 1.8
<p>I hereby certify that this correspondence is being deposited on <u>February 15, 2005</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.</p> <p><u>February 15 2005</u>  Date Signature</p>

Dear Sir:

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The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

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